# CAT28LV64 64K-Bit CMOS PARALLEL EEPROM

## **FEATURES**

- 3.0V to 3.6 V Supply
- Read access times: – 150/200/250ns
- Low power CMOS dissipation:
  - Active: 8 mA max.
  - Standby: 100 μA max.
- Simple write operation:
  - On-chip address and data latches
  - Self-timed write cycle with auto-clear
- Fast write cycle time: - 5ms max.
- Commercial, industrial and automotive temperature ranges

- CMOS and TTL compatible I/O
- Automatic page write operation:
  - 1 to 32 bytes in 5ms
  - Page load timer
- End of write detection: – Toggle bit
  - DATA polling
- Hardware and software write protection

IATALY

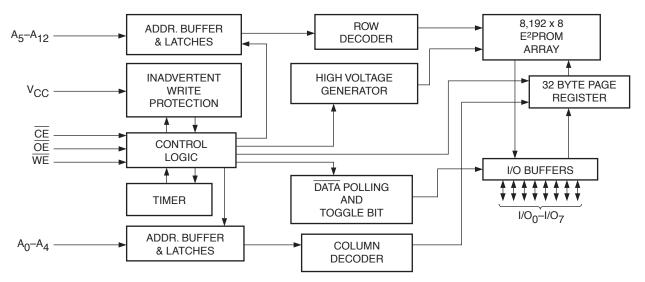
- 100,000 program/erase cycles
- 100 year data retention

## DESCRIPTION

The CAT28LV64 is a low voltage, low power, CMOS parallel EEPROM organized as 8K x 8-bits. It requires a simple interface for in-system programming. On-chip address and data latches, self-timed write cycle with autoclear and  $V_{CC}$  power up/down write protection eliminate additional timing and protection hardware. DATA Polling and Toggle status bit signal the start and end of the self-timed write cycle. Additionally, the CAT28LV64 features hardware and software write protection.

The CAT28LV64 is manufactured using Catalyst's advanced CMOS floating gate technology. It is designed to endure 100,000 program/erase cycles and has a data retention of 100 years. The device is available in JEDEC approved 28-pin DIP, 28-pin TSOP, 28-pin SOIC or 32-pin PLCC packages.

## **BLOCK DIAGRAM**

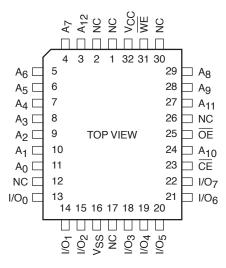


## **PIN CONFIGURATION**

#### DIP Package (P, L)

			1
NC 🗆	•1	28	
A <sub>12</sub> □	2	27	U WE
A7 □	3	26	D NC
A <sub>6</sub> □	4	25	🗆 A <sub>8</sub>
A5 □	5	24	🗆 A9
A4 □	6	23	🗆 A <sub>11</sub>
А <sub>3</sub> 🗆	7	22	
A2 □	8	21	□ A <sub>10</sub>
A₁	9	20	
A <sub>0</sub> □	10	19	□ I/O7
I/O <sub>0</sub>	11	18	□ I/O <sub>6</sub>
I/O <sub>1</sub> □	12	17	□ I/O <sub>5</sub>
I/O <sub>2</sub> □	13	16	□ I/O <sub>4</sub>
$V_{SS}$	14	15	□ I/O <sub>3</sub>

#### PLCC Package (N, G)



OE	1 C
A <sub>11</sub>	2
Ag	3
A <sub>8</sub>	4
NC	5
WE	6
VCC	7
NC	8
A <sub>12</sub>	9
A7	10
A <sub>6</sub>	11
A5	12
A <sub>4</sub>	13
A3	14
	_

#### SOIC Package (J, W) (K, X)

NC 🗂	•1	28	
A <sub>12</sub>	2	27	T WE
A7 [_	3	26	
A <sub>6</sub>	4	25	<u> </u>
A <sub>5</sub>	5	24	<u> </u>
A4 []	6	23	- A <sub>11</sub>
A3 ⊑	7	22	
A <sub>2</sub>	8	21	- A10
A <sub>1</sub> ⊑	9	20	
A <sub>0</sub> [_	10	19	L 1/07
I/O <sub>0</sub>	11	18	1/O <sub>6</sub>
I/O <sub>1</sub>	12	17	☐ I/O <sub>5</sub>
I/O <sub>2</sub>	13	16	<u> </u>
V <sub>SS</sub> []	14	15	[] I/O3

#### TSOP Top View (8mm x 13.4mm) (T13, H13)

	1 0	28	- A <sub>10</sub>
A <sub>11</sub> 🖵	2	27	
A9 🗖	3	26	I/0 <sub>7</sub>
A8 🗖	4	25	1/O <sub>6</sub>
NC	5	24	1/O <sub>5</sub>
WE	6	23	I/04
/cc 🞞	17	22	1/O3
	8	21	GND
A12 🗆	9	20	1/O <sub>2</sub>
A7 🗆	10	19	I/O1
A <sub>6</sub> 🗆	11	18	1/O <sub>0</sub>
A5 🗆	12	17	A0
A4 💷	13	16	A <sub>1</sub>
A3 🖂	14	15	$\square$ A <sub>2</sub>
		_	

#### **PIN FUNCTIONS**

Pin Name	Function	Pin Name	Function
A0-A12	Address Inputs	WE	Write Enable
I/O <sub>0</sub> -I/O <sub>7</sub>	Data Inputs/Outputs	Vcc	3.0 to 3.6 V Supply
CE	Chip Enable	V <sub>SS</sub>	Ground
ŌĒ	Output Enable	NC	No Connect

## **ABSOLUTE MAXIMUM RATINGS\***

Temperature Under Bias –55°C to +125°C
Storage Temperature –65°C to +150°C
Voltage on Any Pin with Respect to Ground <sup>(2)</sup> –2.0V to +V <sub>CC</sub> + 2.0V
V <sub>CC</sub> with Respect to Ground2.0V to +7.0V Package Power Dissipation
Capability (Ta = 25°C) 1.0W
Lead Soldering Temperature (10 secs) 300°C
Output Short Circuit Current <sup>(3)</sup> 100 mA

#### **RELIABILITY CHARACTERISTICS**

## **\*COMMENT**

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions outside of those listed in the operational sections of this specification is not implied. Exposure to any absolute maximum rating for extended periods may affect device performance and reliability.

Symbol	Parameter	Min.	Max.	Units	Test Method
N <sub>END</sub> <sup>(1)</sup>	Endurance	10 <sup>5</sup>		Cycles/Byte	MIL-STD-883, Test Method 1033
T <sub>DR</sub> <sup>(1)</sup>	Data Retention	100		Years	MIL-STD-883, Test Method 1008
V <sub>ZAP</sub> <sup>(1)</sup>	ESD Susceptibility	2000		Volts	MIL-STD-883, Test Method 3015
I <sub>LTH</sub> <sup>(1)(4)</sup>	Latch-Up	100		mA	JEDEC Standard 17

#### **MODE SELECTION**

Mode	CE	WE	ŌĒ	I/O	Power
Read	L	Н	L	D <sub>OUT</sub>	ACTIVE
Byte Write (WE Controlled)	L		Н	D <sub>IN</sub>	ACTIVE
Byte Write (CE Controlled)		L	Н	D <sub>IN</sub>	ACTIVE
Standby, and Write Inhibit	н	Х	Х	High-Z	STANDBY
Read and Write Inhibit	Х	Н	Н	High-Z	ACTIVE

#### CAPACITANCE $T_A = 25^{\circ}C$ , f = 1.0 MHz

Symbol	Test	Max.	Units	Conditions
C <sub>I/O</sub> <sup>(1)</sup>	Input/Output Capacitance	10	pF	$V_{I/O} = 0V$
C <sub>IN</sub> <sup>(1)</sup>	Input Capacitance	6	pF	$V_{IN} = 0V$

Note:

(1) This parameter is tested initially and after a design or process change that affects the parameter.

(2) The minimum DC input voltage is -0.5V. During transitions, inputs may undershoot to -2.0V for periods of less than 20 ns. Maximum DC voltage on output pins is V<sub>CC</sub> +0.5V, which may overshoot to V<sub>CC</sub> +2.0V for periods of less than 20 ns.

(3) Output shorted for no more than one second. No more than one output shorted at a time.

(4) Latch-up protection is provided for stresses up to 100mA on address and data pins from -1V to V<sub>CC</sub> +1V.

#### **D.C. OPERATING CHARACTERISTICS**

 $V_{CC}$  = 3.0V to 3.6V, unless otherwise specified.

			Limits			
Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
Icc	$V_{CC}$ Current (Operating, TTL)			8	mA	$\overline{CE} = \overline{OE} = V_{IL},$ f = 1/t <sub>RC</sub> min, All I/O's Open
I <sub>SBC</sub> <sup>(3)</sup>	V <sub>CC</sub> Current (Standby, CMOS)			100	μΑ	<mark>CE</mark> = V <sub>IHC</sub> , All I/O's Open
ILI	Input Leakage Current	-1		1	μA	$V_{IN} = GND$ to $V_{CC}$
ILO	Output Leakage Current	-5		5	μΑ	$\label{eq:Vout} \begin{array}{l} V_{OUT} = GND \text{ to } V_{CC}, \\ \hline \overline{CE} = V_{IH} \end{array}$
V <sub>IH</sub> <sup>(3)</sup>	High Level Input Voltage	2		V <sub>CC</sub> +0.3	V	
VIL	Low Level Input Voltage	-0.3		0.6	V	
V <sub>OH</sub>	High Level Output Voltage	2			V	I <sub>OH</sub> = -100μA
V <sub>OL</sub>	Low Level Output Voltage			0.3	V	$I_{OL} = 1.0 \text{mA}$
Vwi	Write Inhibit Voltage	2			V	

#### A.C. CHARACTERISTICS, Read Cycle

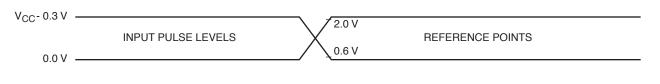
 $V_{CC}$  = 3.0V to 3.6V, unless otherwise specified.

		28LV64-15		28LV	64-20	20 28LV64-25		
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Units
t <sub>RC</sub>	Read Cycle Time	150		200		250		ns
t <sub>CE</sub>	CE Access Time		150		200		250	ns
t <sub>AA</sub>	Address Access Time		150		200		250	ns
toE	OEAccess Time		70		80		100	ns
t <sub>LZ</sub> (1)	CE Low to Active Output	0		0		0		ns
t <sub>OLZ</sub> <sup>(1)</sup>	OE Low to Active Output	0		0		0		ns
t <sub>HZ</sub> <sup>(1)(2)</sup>	CE High to High-Z Output		50		50		55	ns
t <sub>OHZ</sub> <sup>(1)(2)</sup>	OE High to High-Z Output		50		50		55	ns
t <sub>OH</sub> <sup>(1)</sup>	Output Hold from Address Change	0		0		0		ns

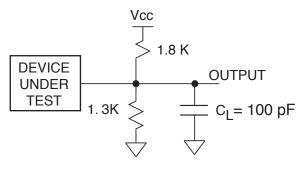
Note:

(1) This parameter is tested initially and after a design or process change that affects the parameter. (2) Output floating (High-Z) is defined as the state when the external data line is no longer driven by the output buffer. (3)  $V_{IHC} = V_{CC} - 0.3V$  to  $V_{CC} + 0.3V$ .

## Figure 1. A.C. Testing Input/Output Waveform<sup>(4)</sup>



## Figure 2. A.C. Testing Load Circuit (example)



C<sub>1</sub> INCLUDES JIG CAPACITANCE

## A.C. CHARACTERISTICS, Write Cycle

 $V_{cc}$  = 3.0V to 3.6V, unless otherwise specified.

		28LV64-15		28LV64-20		28LV64-25			
Symbol	Parameter	Min	Max	Min	Max	Min	Max	Units	
twc	Write Cycle Time		5		5		5	ms	
tas	Address Setup Time0	0		0		0		ns	
tан	Address Hold Time	100		100		100		ns	
tcs	CE Setup Time	0		0		0		ns	
tсн	CE Hold Time	0		0		0		ns	
tcw <sup>(2)</sup>	CE Pulse Time	110		150		150		ns	
toes	OE Setup Time	0		10		10		ns	
tоен	OE Hold Time	0		10		10		ns	
twP <sup>(2)</sup>	WE Pulse Width	110		150		150		ns	
tDS	Data Setup Time	60		100		100		ns	
tDH	Data Hold Time	0		0		0		ns	
t <sub>INIT</sub> (1)	Write Inhibit Period After Power-up	5	10	5	10	5	10	ms	
t <sub>BLC</sub> <sup>(1)(3)</sup>	Byte Load Cycle Time	0.05	100	0.1	100	0.1	100	μs	

Note:

(1) This parameter is tested initially and after a design or process change that affects the parameter.

(2) A write pulse of less than 20ns duration will not initiate a write cycle.

(3) A timer of duration  $t_{BLC}$  max. begins with every LOW to HIGH transition of  $\overline{WE}$ . If allowed to time out, a page or byte write will begin; however a transition from HIGH to LOW within  $t_{BLC}$  max. stops the timer.

(4) Input rise and fall times (10% and 90%) < 10 ns.

## **DEVICE OPERATION**

#### Read

Data stored in the CAT28LV64 is transferred to the data bus when  $\overline{WE}$  is held high, and both  $\overline{OE}$  and  $\overline{CE}$  are held low. The data bus is set to a high impedance state when either  $\overline{CE}$  or  $\overline{OE}$  goes high. This 2-line control architecture can be used to eliminate bus contention in a system environment.

#### Figure 3. Read Cycle

#### **Byte Write**

A write cycle is executed when both  $\overline{CE}$  and  $\overline{WE}$  are low, and  $\overline{OE}$  is high. Write cycles can be initiated using either  $\overline{WE}$  or  $\overline{CE}$ , with the address input being latched on the falling edge of  $\overline{WE}$  or  $\overline{CE}$ , whichever occurs last. Data, conversely, is latched on the rising edge of  $\overline{WE}$  or  $\overline{CE}$ , whichever occurs first. Once initiated, a byte write cycle automatically erases the addressed byte and the new data is written within 5 ms.

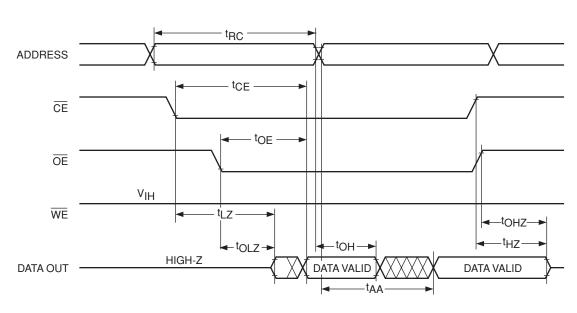
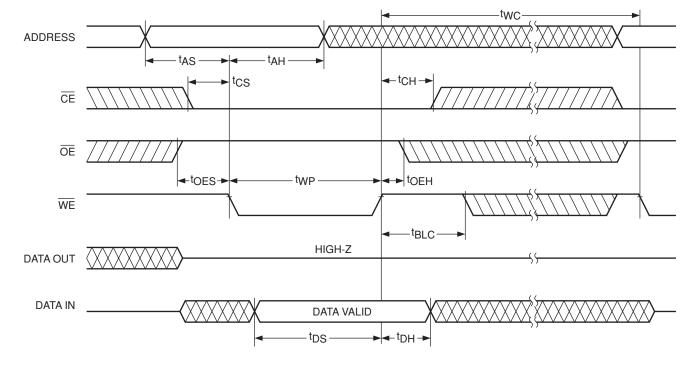


Figure 4. Byte Write Cycle [WE Controlled]



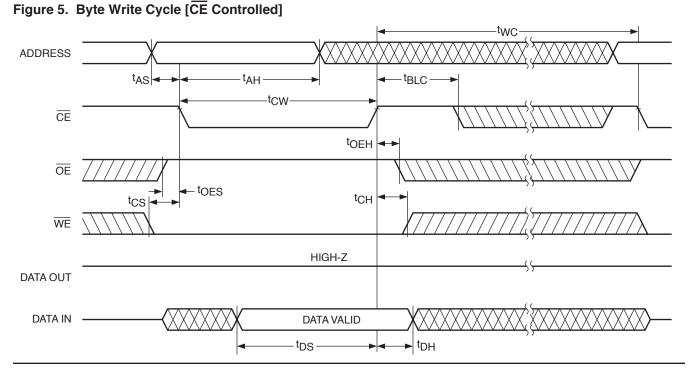
### Page Write

The page write mode of the CAT28LV64 (essentially an extended BYTE WRITE mode) allows from 1 to 32 bytes of data to be programmed within a single EEPROM write cycle. This effectively reduces the byte-write time by a factor of 32.

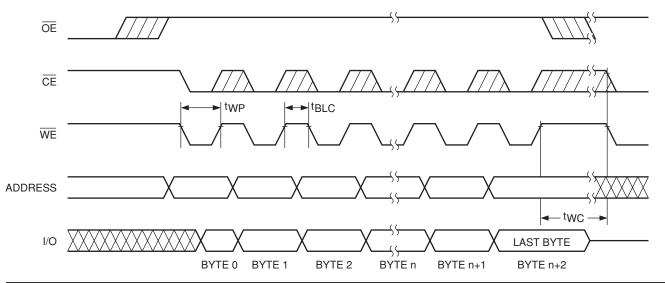
Following an initial WRITE operation (WE pulsed low, for t<sub>WP</sub>, and then high) the page write mode can begin by issuing sequential WE pulses, which load the address and data bytes into a 32 byte temporary buffer. The page address where data is to be written, specified by bits A<sub>5</sub> to A<sub>12</sub>, is latched on the last falling edge of WE. Each byte within the page is defined by address bits A<sub>0</sub> to A<sub>4</sub>

(which can be loaded in any order) during the first and subsequent write cycles. Each successive byte load cycle must begin within  $t_{BLC\,MAX}$  of the rising edge of the preceding  $\overline{WE}$  pulse. There is no page write window limitation as long as  $\overline{WE}$  is pulsed low within  $t_{BLC\,MAX}$ .

Upon completion of the page write sequence,  $\overline{\text{WE}}$  must stay high a minimum of  $t_{\text{BLCMAX}}$  for the internal automatic program cycle to commence. This programming cycle consists of an erase cycle, which erases any data that existed in each addressed cell, and a write cycle, which writes new data back into the cell. A page write will only write data to the locations that were addressed and will not rewrite the entire page.





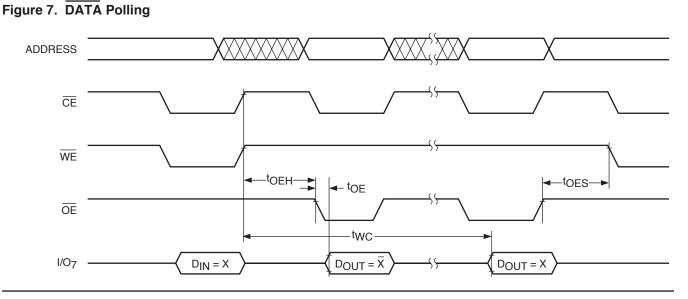


## DATA Polling

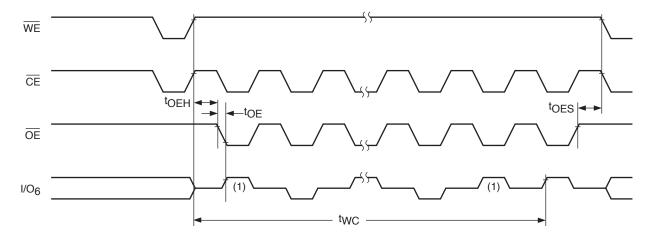
DATA polling is provided to indicate the completion of write cycle. Once a byte write or page write cycle is initiated, attempting to read the last byte written will output the complement of that data on  $I/O_7$  ( $I/O_0$ – $I/O_6$  are indeterminate) until the programming cycle is complete. Upon completion of the self-timed write cycle, all I/O's will output true data during a read cycle.

## Toggle Bit

In addition to the DATA Polling feature, the device offers an additional method for determining the completion of a write cycle. While a write cycle is in progress, reading data from the device will result in  $I/O_6$  toggling between one and zero. However, once the write is complete,  $I/O_6$ stops toggling and valid data can be read from the device.



#### Figure 8. Toggle Bit



Note:

(1) Beginning and ending state of  $I/O_6$  is indeterminate.

#### HARDWARE DATA PROTECTION

The following is a list of hardware data protection features that are incorporated into the CAT28LV64.

- (1)  $V_{CC}$  sense provides for write protection when  $V_{CC}$  falls below 2.0V min.
- (2) A power on delay mechanism,  $t_{INIT}$  (see AC characteristics), provides a 5 to 10 ms delay before a write sequence, after V<sub>CC</sub> has reached 2.40V min.
- (3) Write inhibit is activated by holding any one of OE low, CE high or WE high.

#### Figure 9. Write Sequence for Activating Software Data Protection

WRITE DATA: AA ADDRESS: 1555 WRITE DATA: 55 ADDRESS: 0AAA WRITE DATA: A0 ADDRESS: 1555 SOFTWARE DATA PROTECTION ACTIVATED (1) WRITE DATA: ΧХ TO ANY ADDRESS WRITE LAST BYTE TO LAST ADDRESS

## 28LV64 F12

Note:

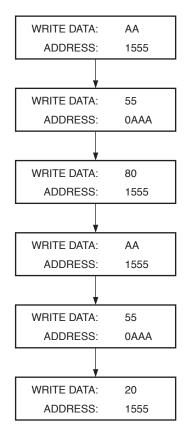
(1) Write protection is activated at this point whether or not any more writes are completed. Writing to addresses must occur within t<sub>BLC</sub> Max., after SDP activation.

(4) Noise pulses of less than 20 ns on the WE or CE inputs will not result in a write cycle.

#### SOFTWARE DATA PROTECTION

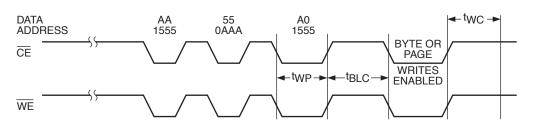
The CAT28LV64 features a software controlled data protection scheme which, once enabled, requires a data algorithm to be issued to the device before a write can be performed. The device is shipped from Catalyst with the software protection NOT ENABLED (the CAT28LV64 is in the standard operating mode).

#### Figure 10. Write Sequence for Deactivating Software Data Protection

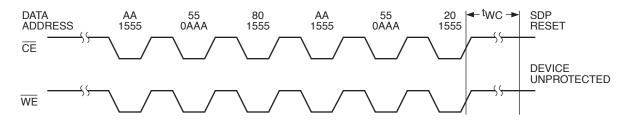


To activate the software data protection, the device must be sent three write commands to specific addresses with specific data (Figure 9). This sequence of commands (along with subsequent writes) must adhere to the page write timing specifications (Figure 11). Once this is done, all subsequent byte or page writes to the device must be preceded by this same set of write commands. The data protection mechanism is activated until a deactivate sequence is issued regardless of power on/off transitions. This gives the user added inadvertent write protection on power-up in addition to the hardware protection provided. To allow the user the ability to program the device with an EEPROM programmer (or for testing purposes) there is a software command sequence for deactivating the data protection. The six step algorithm (Figure 10) will reset the internal protection circuitry, and the device will return to standard operating mode (Figure 12 provides reset timing). After the sixth byte of this reset sequence has been issued, standard byte or page writing can commence.

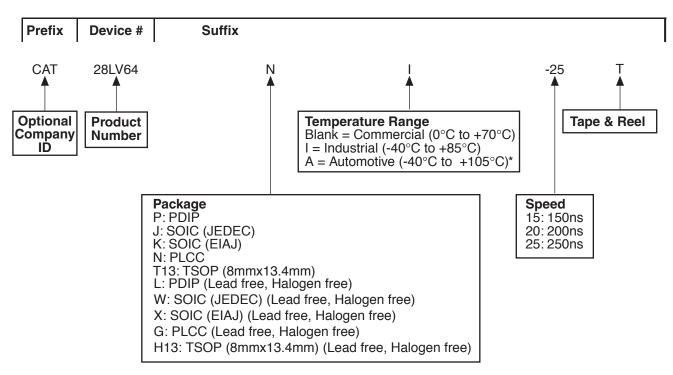
#### Figure 11. Software Data Protection Timing







## **ORDERING INFORMATION**



 $^{*}$  -40°C to +125°C is available upon request

Notes:

(1) The device used in the above example is a CAT28LV64NI-25T (PLCC, Industrial temperature, 250 ns Access Time, Tape & Reel).

## **REVISION HISTORY**

Date	Revision	Comments
3/29/04	С	Added Green packages in all areas
04/20/04	D	Delete data sheet designation
		Update Ordering Information
		Update Revision History
		Update Rev Number

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